

What is claimed is:

1. A heat dissipation module of an interface card, the heat dissipation module comprising:

a heat sink having a base abutting an electrical component of the interface card, a plurality of fins outwardly extending from each side of the base, at least one holding portion having a connecting arm outwardly extending from a side of the base, two symmetrical retaining arm respectively outwardly extending from an end of the connecting arm and a receiving space defined by the two retaining arm; and

at least one hooking device received in the receiving space of the at least one holding portion for hooking the heat sink on the interface card.

2. The heat dissipation module of the interface card as claimed in claim 1, wherein the heat sink is made by aluminum extrusion.

3. The heat dissipation module of the interface card as claimed in claim 1, wherein the at least one hooking device has a member sleeve having a sleeve body and a circular portion outwardly protruding along a rim of a top of the sleeve body, a spring compressedly received in the sleeve body of the member sleeve, and a hooking member inserted into the spring and an opening of a bottom of the sleeve body for hooking the heat sink on the interface card.

4. The heat dissipation module of the interface card as claimed in claim 3, wherein the hooking member has a hooking member body, a retaining portion outwardly protruding along a rim of a top of the hooking member body, two

hooks symmetrically formed on a bottom of the hooking member body, and a notch defined by the two hooks.

5 5. The heat dissipation module of the interface card as claimed in claim 1, further comprising a fan mounted on the heat sink for providing air to cool the heat sink.

6. A heat sink of a heat dissipation module of an interface card, the heat sink comprising:

a base abutting an electrical component of the interface card, and a plurality of fins outwardly extending from each side of the base.

10 7. The heat sink of the heat dissipation module of the interface card as claimed in claim 6, wherein the heat sink is made by aluminum extrusion.

8. The heat sink of the heat dissipation module of the interface card as claimed in claim 7, further comprising at least one holding portion outwardly extending from a side of the base.

15 9. The heat sink of the heat dissipation module of the interface card as claimed in claim 8, wherein the at least one holding portion has a connecting arm outwardly extending from the side of the base, two symmetrical retaining arm respectively outwardly extending from an end of the connecting arm and a receiving space defined by the two retaining arm.